Overview

HP Elite Dragonfly Max



- 1. Internal Microphones
- 2. IR Camera LEDs
- 3. Webcam and IR Camera
- 4. Privacy Camera Shutter
- 5. Webcam LED

Left

- 6. Glass Clickpad
- 7. WWAN SIM (Nano)
- **8.** Nano Security Lock Slot (Lock sold separately)
- 9. Power Button
- 10. SuperSpeed USB Type-A 5Gbps signaling rate

Overview



Right

- HDMI 2.0 port (Cable not included) 1.
- 2. Audio Combo Jack
- Thunderbolt[™] 4 with USB4 Type-C[®] 40Gbps signaling 3. rate (USB Power Delivery, DisplayPort™ 1.4)1
 - 1. SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4.
- Thunderbolt[™] 4 with USB4 Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPort™ 1.4)¹
- Touch Fingerprint Sensor (Select models)

Overview

AT A GLANCE

- Preinstalled Windows 10 Pro (64 bit), Windows 10 Home (64 bit), FreeDOS 3.0
- Choice of 11th Generation Intel® Core™ i7 supporting, vPro® and non vPro®
- Ultraslim x360 with 100% touch (10-Point Multi-Touch), chemically- strengthened Corning® Gorilla® Glass 5, direct bond; 13.3" diagonal HP Sure View Reflect with Anti-Sparkle, Brightview 1000 nits
- Integrated Intel® HD Graphics
- Enhanced security features including 2021 HP Sure Start, HP Sure View, HP Sure Click, HP Sure Recover, Sure BIO, hardware TPM 2.0, touch fingerprint sensor, face recognition with IR camera, Nano lock slot, wake on FPS, intrusion detection
- Passed MIL-STD 810H¹ testing
- Weight starting at 2.49 lb
- 4 cell long life polymer 56.2Wh battery
- Supports wireless LAN and wireless WAN options for connectivity on the go, including 5G
- From 256 GB up to 2 TB Solid State Drives
- 16 GB/32 GB LPDDR4 total system memory
- 5MP + IR webcam, face authentication, Windows Hello certified; HP Privacy Camera
- HP Quiet Keyboard (1.3mm travel), full-size, spill-resistant, ambient light-sensing backlight keyboard with integrated lattice, HP DuraKeys, ClickPad - MS PTP, optional HP Rechargeable Active Pen with USB-A holder)
- HP Eye Ease Low Blue Light
- Wide-range Mic Array (4x mics two front-facing and two world-facing)
- Recycled material, ocean-bound plastics

1. MIL-STD 810H is not intended to demonstrate fitness of U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Technical Specifications

PRODUCT NAME

HP Elite Dragonfly Max

PRODUCT COLORS

Sparkling Black

OPERATING SYSTEM

Preinstalled Windows 10 Pro 64 – HP recommends Windows 10 Pro for business¹

Windows 10 Home 64¹

FreeDOS

1. Not all features are available in all editions or versions of Window. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.

NOTE: HP tested Windows 10, version 1909 on this platform. For testing information on newer versions of Windows 10, please see https://support.hp.com/document/c05195282.

PROCESSORS

Intel® Core™ i7-1185G7 (3.0 GHz base frequency, up to 4.8 GHz frequency with Intel® Turbo Boost Technology, 12 MB L3 cache, 4 cores), supports Intel® vPro® Technology^{2,3,45}

Intel® Core™ i7-1165G7 (2.8 GHz base frequency, up to 4.7 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 4 cores)^{2,3,45}

Processor Family

11th Generation Intel® Core™ i7 processor (i7- 1185G7, i7- 1165G7)⁵

- 2. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- 3. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
- 4. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information.
- 5. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.



Technical Specifications

CHIPSET

Chipset is integrated with processor

GRAPHICS

Integrated

Intel® Iris® Xe Graphics6

Supports

Support HD decode, DX12, HDMI 2.07

6. Intel® Iris® Xe Graphics capabilities require system to be configured with Intel® Core™ i7 processors and dual channel memory. Intel® Iris® Xe Graphics with Intel® Core™ i7 processors and single channel memory will only function as UHD graphics.

7. HDMI cable sold separately.

DISPLAY

Touch

33.8 cm (13.3") diagonal FHD bent, Anti-Sparkle WLED UMA eDP 1.4+PSR, Brightview 1000 nits, 100% sRGB, Touch with HP Sure View Reflect integrated privacy screen (1920 x 1080), HP Eye Ease Low Blue Light 8,9,10,11,47

- 8. FHD/HD content required to view FHD/HD images.
- 9. Resolutions are dependent upon monitor capability, and resolution and color depth settings.
- 10. Actual brightness will be lower with touchscreen or Sure View.
- 11. HP Sure View integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.
- 47. Your computer display is shipped from the factory in low blue light mode for improved eye comfort and safety. Also, blue light mode automatically adjusts blue light emissions when you are using the computer at night or for reading.

STORAGE AND DRIVES

Primary M.2 Storage

2 TB PCle® Gen3x4 NVMe[™] M.2 SSD TLC¹²
1 TB PCle® Gen3x4 NVMe[™] M.2 SSD TLC¹²
512 GB PCle® Gen3x4 NVMe[™] M.2 SSD TLC¹²

256 GB PCIe® NVMe™ Value M.2 SSD 12

12. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.



Technical Specifications

MEMORY

Maximum Memory

32 GB LPDDR4X-4266 SDRAM13

Memory

32 GB LPDDR4X-4266 SDRAM¹³ 16 GB LPDDR4X-4266 SDRAM¹³

Memory Slots

LPDDR4X, system runs at 4266 Supports Dual Channel Memory

13. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WLAN

Intel® Dual Band Wi-Fi® 6 AX201 802.11a/b/g/n/ac/ax (2x2) WLAN and Bluetooth® 5 Combo, vPro® 14 Intel® Dual Band Wi-Fi® 6 AX201 802.11a/b/g/n/ac/ax (2x2) WLAN and Bluetooth® 5 Combo, non-vPro® 14

WWAN

Intel® XMM[™] 7360 LTE-Advanced Cat 9¹⁶
Qualcomm® Snapdragon[™] X55 5G LTE Cat 20¹⁷

Miracast

Native Miracast Support¹⁸

14. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported.

16. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

17. 5G module is an optional feature that must be configured at purchase. AT&T and T-Mobile networks supported in the U.S. Module designed for 5G networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity.

17. 5G module is an optional feature that must be configured at purchase. AT&T and T-Mobile networks supported in the U.S. Module designed for 5G networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP, requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 5G not available on all products, in all regions. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select countries, where carrier supported.

18. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.



Technical Specifications

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen 4 digital Microphones 4 Integrated stereo speakers

Camera

Dual Array Digital Microphone 5MP USB2 Infrared Integrated Camera

Sensors

Ambient light sensor
Hall effect sensor
HP Tamper Lock¹⁵
Magnetometer
Accelerometer + Gyroscope + eCompass
IC Accelerometer HP2DCTR LGA-12
IR Thermal Sensor

15. HP Tamper Lock must be enabled by the customer or your administrator.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Modernized Keyboard, spill resistant, Backlit Backlit, Spill-resistant, with HP Dura Keys

Pointing Device

Glass Clickpad

Microsoft Precision Touchpad Default Gestures Support

Function Keys

F1 - Display Switching

F2 - Blank or Privacy

F3 - Brightness Down

F4 - Brightness Up

F5 - Audio Mute

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute

Backlit Toggle

F10 - Insert

F11 - Airplane Mode

F12 - HP Command Center (Programmable Key)

Num Lock

Print Screen

Delete



Technical Specifications

SOFTWARE AND SECURITY

Preinstalled Software

BIOS

HP BIOSphere Gen6 19

HP Drive Lock & Automatic Drive Lock

BIOS Update via Network

HP Secure Erase 20

Absolute Persistence Module 21

HP LAN-Wireless Protection

USB enable/disable (via BIOS)

Software

HP Connection Optimizer 22

HP Hotkey Support

myHP

HP Support Assistant 23

HP QuickDrop 27

HP Noise Cancellation Software

Touchpoint Customizer for Commercial

HP Notifications

HP Privacy Settings

HP Wireless Button Driver

HP Power Manager

Tile App 24

HP PC Hardware Diagnostics Windows

Buy Microsoft Office (sold separately)

Microsoft Defender

HP Smart Support 49

Manageability Features

HP Driver Packs (download) 25

HP Manageability Integration Kit Gen4 (download) 26

HP Client Catalog (download)

HP Client Management Script Library (download)

HP Image Assistant (download)

Security Management

HP Fingerprint Sensor 28

HP Wolf Pro Security Edition 29

HP Sure Click 30

HP Sure Sense 31

HP Sure Start Gen6 32

HP Sure Admin 33

HP Sure Recover Gen4 34

HP Sure Run Gen4 35

HP Client Security Manager Gen7³⁶

TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified)

Secured-Core PC Enable⁴⁶

Technical Specifications

- 19. HP BIOSphere Gen6 requires Windows 10 and is available on select HP Pro and Elite PCs. Features may vary depending on the platform and configurations.
- 20. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
- 21. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit:

https://www.absolute.com/about/legal/agreements/absolute/.

- 22. HP Connection Optimizer requires Windows 10.
- 23. HP Support Assistant internet access required.
- 24. Tile is an optional feature that must be configured at the factory and requires Windows 10. Some features require optional subscription to Tile Premium. Tile application for Windows 10 available for download from the Windows Store. Mobile phone app available for download from App Store and Google Play. Requires iOS 11 and greater or Android 6.0 and greater see https://support.thetileapp.com/hc/en-us/articles/200424778 for more information. HP Tile will function as long as the PC has battery power.
- 25. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- 26. HP Manageability Integration Kit can be downloaded from

http://www8.hp.com/us/en/ads/clientmanagement/overview.html.

- 27. Quick Drop requires Internet access and Windows 10 PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app.
- 28. HP Fingerprint sensor is an optional feature that must be configured at purchase.
- 29. HP Wolf Pro Security Edition (including HP Sure Click Pro and HP Sure Sense Pro) is available preloaded on select SKUs and, depending on the HP product purchased, includes a paid 1-year or 3-year license. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-en/document/ish_3875769-3873014-16 as that EULA is modified by the following: "7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for either a twelve (12) month or thirty-six (36) month license term ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support.30. HP Sure Click requires Windows 10 Pro or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.
- 31. HP Sure Sense is available on select HP PCs and is not available with Windows10 Home.
- 32. HP Sure Start Gen6 is available on select HP PCs and requires Windows 1033. HP Sure Admin requires Windows 10, HP BIOS, HP Manageability Integration Kit from http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.
- 34. HP Sure Recover Gen4 is available on select HP PCs and requires an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module.
- 35. HP Sure Run Gen4 is available on select HP PCs and requires Windows 10.
- 36. HP Client Security Manager Gen7 requires Windows and is available on the select HP Elite and Pro PCs.
- 46. Secured-core PC enable requires an Intel® vPro®, AMD Ryzen™ Pro processor or Qualcomm® processor with SD850 or higher and requires 8 GB or more system memory. Secured-core PC functionality can be enabled from the factory.

 49. HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory
- 49. HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: http://www.hp.com/smart-support. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.



Technical Specifications

POWER

Power Supply

HP Smart 65 W USB Type-C adapter ³⁷ HP Smart 65 W Slim USB Type-C adapter ³⁷

Primary Battery

HP Long Life 4-cell, 56Wh polymer ^{38,39}
HP Fast Charge Technology (50% in 30 minutes) ⁴⁰

Power Cord

1.0m power cord

Battery Life⁴¹

Up to 13 hours and 15 minutes

Battery Weight

0.259 kg

- 37. Availability may vary by country.
- 38. Battery is internal and not replaceable by customer. Serviceable by warranty.
- 39. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.
- 40. Supports HP Fast Charge with 65W AC Adapter. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.
- 41. Windows 10 MM18 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See www.bapco.com for additional details.

WEIGHTS & DIMENSIONS

Product Weight

Starting at 2.49 lb (1.13 kg)42

Product Dimensions (w x d x h)

11.98 x 7.78 x 0.63 in 30.43 x 19.75 x 1.61 cm

42. Weight will vary by configuration.



Technical Specifications

PORTS/SLOTS

Ports

2 Thunderbolt™ 4 with USB4 Type-C® 40Gbps signaling rate (USB Power Delivery, DisplayPort™ 1.4)⁴⁸

1 SuperSpeed USB Type-A 5Gbps signaling rate (Charging port)

1 Headphone/microphone combo jack

1 HDMI 2.07

7. HDMI cable sold separately.

48. SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4.

SERVICE AND SUPPORT

1-year and 3-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for HP Long Life batteries which will follow the one or three year warranty of the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc. 43

43. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications

CERTIFICATION AND COMPLIANCE

ENERGY STAR® certified ⁴⁴ EPEAT® 2019 Gold in the U.S. ⁴⁵ TCO 8.0 Certified

44. Configurations of the HP Elite Dragonfly Max that are ENERGY STAR® qualified are identified as HP Elite Dragonfly Max ENERGY STAR on HP websites and on http://www.energystar.gov.

45. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information.

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	Nominal Operating Voltage	20V, 3.25A
	Integrated Graphics	Intel UMA
	Max Operating Power	UMA
Temperature	Operating	32° to 95° F (0° to 35° C)
	Non-operating	41° to 95° F (5° to 35° C) (writing optical)
Shock	Non-operating	Comply SVTP
	Operating	Comply SVTP
Random Vibration	Non-operating	Comply SVTP
	Operating	Comply SVTP
Altitude (unpressurized)	Non-operating	Comply SVTP



Technical Specifications

DISPLAYS

1. Actual brightness will be lower with touchscreen or Sure View.

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

13.3 in FHD (1920 x 1080) Anti-Sparkle UWVA sRGB NB2Y 1000 eDP 1.4+PSR 100 PrivacyG4 Plus bent LCD Panel **Outline Dimensions (W x H)** 299.06 x 175.14 mm (max)

Active Area 293.76 x 165.24 mm

Weight 220 g (max)

Diagonal Size 13.3 inch

Thickness 3.9 mm (max)

Interface eDP 1.4 + PSR (4 lane)

Surface Treatment Anti-Sparkle

Touch Enabled Yes
Contrast Ratio 1500:1
Refresh Rate 60 Hz

Brightness 1000 nits ¹

Pixel Resolution 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB

Backlight LED

Color Gamut Coverage 72%

Color Depth 8 bits

Viewing Angle UWVA 85/85/85



Technical Specifications

STORAGE

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

SSD 1TB 2280 PCIe-3x4 NVMe Three Layer Cell single-sided Form Factor M.2 2280
Capacity 1 TB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCle NVMe Gen3X4

 Maximum Sequential Read
 Up To 2800 MB/s

 Maximum Sequential Write
 Up To 1600 MB/s

 Logical Blocks
 2,000,409,264

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option); TRIM; L1.2

SSD 2TB 2280 PCIe-3x4 NVMe Three Layer Cell single-sided Form Factor M.2 2280
Capacity 2 TB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

 Maximum Sequential Read
 Up To 3000 MB/s

 Maximum Sequential Write
 Up To 2100 MB/s

 Logical Blocks
 3,907,029,168

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG OPAL 2.0; DIPM; TRIM; DEVSLP

Technical Specifications

SSD 512GB 2280 M2 PCIe-3x4 SS Form Factor NVMe TLC

Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

Maximum Sequential Read $2800 \text{ MB/s} \sim 2900 \text{ MB/s}$ Maximum Sequential Write $1000 \text{ MB/s} \sim 1800 \text{ MB/s}$

Logical Blocks 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option); TRIM; L1.2

SSD 256GB 2280 PCIe NVMe Value Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe

Maximum Sequential ReadUp To 1700 MB/sMaximum Sequential WriteUp to 1300 MB/sLogical Blocks500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security, TRIM; L1.2



Technical Specifications

NETWORKING/COMMUNICATIONS

Intel® Wi-Fi 6¹ AX201 + BT5 (802.11ax 2x2, vPro®, supporting gigabit data speed⁵) (vPro®) **Wireless LAN Standards**

IEEE 802.11a
IEEE 802.11b
IEEE 802.11g
IEEE 802.11n

IEEE 802.11ac
IEEE 802.11d
IEEE 802.11e
IEEE 802.11h
IEEE 802.11i
IEEE 802.11k
IEEE 802.11r
IEEE 802.11r

Interoperability Features Wi-Fi 6 technology

Frequency Band 802.11b/g/n/ax

•2.402 – 2.482 GHz 802.11a/n/ac/ax

•4.9 – 4.95 GHz (Japan)

•5.15 – 5.25 GHz •5.25 – 5.35 GHz •5.47 – 5.725 GHz •5.825 – 5.850 GHz

Data Rates •802.11b: 1, 2, 5.5, 11 Mbps

•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

 \bullet 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

, 1024QAM

•IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only

•AES-CCMP: 128 bit in hardware

•802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

•WPA2 certification
•IEEE 802.11i

•WAPI

Technical Specifications

Network Architecture

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Roaming

IEEE 802.11 compliant roaming between access points

Output Powe²r

802.11b: +18.5dBm minimum
802.11g: +17.5dBm minimum
802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum
802.11ac VHT160(5GHz): +11.5dBm minimum
802.11ax HT40(2.4GHz): +10dBm minimum
802.11ax VHT160(5GHz): +10dBm minimum

Power Consumption

•Transmit mode:2.0 W

•Receive mode:1.6 W

Idle mode (PSP)180 mW (WLAN Associated)
 Idle mode:50 mW (WLAN unassociated)
 Connected Standby/Modern Standby: 10mW

Radio disabled: 8 mW

Power Management

ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity⁴

802.11b, 1Mbps: -93.5dBm maximum
802.11b, 11Mbps: -84dBm maximum
802.11a/g, 6Mbps: -86dBm maximum
802.11a/g, 54Mbps: -72dBm maximum
802.11n, MCS07: -67dBm maximum
802.11n, MCS15: -64dBm maximum
802.11ac, MCS0: -84dBm maximum

802.11ac, MCS9: -59dBm maximum
 802.11ax, MCS11(HT40): -59dBm maximum
 802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna type

High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard with CNVi Interface

Dimensions 1. Type 2230: 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230: 2.8g

Technical Specifications

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (–10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

LED Amber – Radio OFF; LED White – Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0/5.1 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available

Channels

Legacy: 0~79 (1 MHz/CH)

BLE: 0~39 (2 MHz/CH)

Signaling Data Rate Legacy: 3 Mbps data rate¹; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate¹; throughput up to 0.2 Mbps

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 9.5 dBm for BR and EDR.

Power Consumption Peak (Tx): 330 mW

Peak (Rx): 230 mW

Selective Suspend: 17 mW

Bluetooth Software

Supported

Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support

Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management

Certifications

ETS 300 328, ETS 300 826

Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles

Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping

LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising



Technical Specifications

LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full

LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2

Headset Profile (HSP)

Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Security & Manageability Intel® vPro™ support with appropriate Intel® chipset components

- 1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported.
- 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 3. Check latest software/driver release for updates on supported security features.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
- 5. Wi-Fi 5 or 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.



(non-vPro®)

Technical Specifications

Intel® Wi-Fi® ¹ 6 AX201 + Wireless LAN Standards BT5 (802.11ax 2x2, nonvPro®, supporting gigabit data ratespeeds⁵)

IEEE 802.11b IEEE 802.11g IEEE 802.11n

IEEE 802.11a

IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11r

Interoperability Features Wi-Fi 6 technology

Frequency Band 802.11b/g/n/ax

•2.402 – 2.482 GHz 802.11a/n/ac/ax •4.9 – 4.95 GHz (Jan

•4.9 – 4.95 GHz (Japan) •5.15 – 5.25 GHz

•5.25 – 5.35 GHz •5.47 – 5.725 GHz •5.825 – 5.850 GHz

Data Rates •802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

, 1024QAM

Security³ •IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only

•AES-CCMP: 128 bit in hardware

•802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

•WPA2 certification •IEEE 802.11i

•WAPI

Network Architecture Ad-hoc (Peer to Peer)

Models



Technical Specifications

Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

Output Power² • 802.11b: +18.5dBm minimum

802.11g: +17.5dBm minimum
802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum
802.11ac VHT160(5GHz): +11.5dBm minimum

802.11ax HT40(2.4GHz): +10dBm minimum
 802.11ax VHT160(5GHz): +10dBm minimum

Power Consumption • Transmit mode 2.0 W

•Receive mode 1.6 W

•Idle mode (PSP) 180 mW (WLAN Associated)
•Idle mode 50 mW (WLAN unassociated)

•Connected Standby 10mW

Radio disabled 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity⁴ •802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum
802.11a/g, 6Mbps: -86dBm maximum
802.11a/g, 54Mbps: -72dBm maximum
802.11n, MCS07: -67dBm maximum
802.11n, MCS15: -64dBm maximum
802.11ac, MCS0: -84dBm maximum

• 802.11ac, MCS9 : -59dBm maximum

•802.11ax, MCS11(HT40): -59dBm maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard with CNVi Interface

Dimensions 1. Type 2230: 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230: 2.8g

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

Technical Specifications

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)"

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)"

LED Activity LED Amber – Radio OFF; LED Off – Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0/5.1 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available

Channels

Legacy: 0~79 (1 MHz/CH)

BLE: 0~39 (2 MHz/CH)

Signaling Data Rate Legacy: 3 Mbps data rate¹; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate¹; throughput up to 0.2 Mbps

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 9.5 dBm for BR and EDR.

Power Consumption Peak (Tx): 330 mW

Peak (Rx): 230 mW

Selective Suspend: 17 mW

Bluetooth Software

Supported

Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support

Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management

Certifications

Supported

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles

Profiles BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping

LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising
LE L2CAP Connection Oriented Channels

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Technical Specifications

Oualcomm® Snapdragon™ X55 5G Modem (5G + LTE CAT 20) Technology/Operating **hands**

WCDMA/HSDPA/HSUPA/HSPA+ operating bands:

Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL) Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) Band 6: 830 to 840 MHz (UL), 875 to 885 MHz (DL) Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL) Band 9: 1750 to 1785 MHz(UL), 1845to 1880 MHz (DL) Band 19: 830 to 845 MHz (UL), 875 to 890 MHz (DL)

LTE FDD/TDD operating bands: Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) Band 3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL) Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL) Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) Band 7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL) Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL) Band 12: 699 to 716 MHz (UL), 729 to 746 MHz (DL) Band 13: 777 to 787 MHz (UL), 746 to 756 MHz (DL) Band 14: 788 to 798 MHz (UL), 758 to 768 MHz (DL) Band 17: 704 to 716 MHz (UL), 734 to 746 MHz (DL) Band 18: 815 to 830 MHz (UL), 860 to 875 MHz (DL) Band 19: 830 to 845 MHz (UL), 875 to 890 MHz (DL) Band 20: 832 to 862 MHz (UL), 791 to 821 MHz (DL) Band 25: 1850 to 1915 MHz (UL), 1930 to 1995 MHz (DL) Band 26: 814 to 849 MHz (UL), 859 to 894 MHz (DL) Band 28: 703 to 748 MHz (UL). 758 to 803 MHz (DL) Band 29: 717 to 728 MHz (DL) Band 30: 2305 to 2315 MHz (UL) 2350 to 2360 MHz (DL) Band 32: 1452 to 1496 MHz (DL) Band 34: 2010 to 2025 MHz (UL/DL) Band 38: 2570 to 2620 MHz (UL/DL) Band 39: 1880 to 1920 MHz (UL/DL) Band 40: 2300 to 2400 MHz (UL/DL) Band 41: 2496 to 2690 MHz (UL/DL) Band 42: 3400 to 3600 MHZ (UL/DL) Band 46: 5150 to 5925 MHZ (DL) Band 48: 3550 to 3700 MHZ (UL/DL) Band 66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL) Band 71: 663 to 698 MHz (UL), 617 to 652 MHz (DL)



Technical Specifications

5GNR Sub 6GHZ:

n1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL)
n2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL)
n3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL)
n5: 824 to 849 MHz (UL), 869 to 894 MHz (DL)
n7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL)
n8: 880 to 915 MHz (UL), 925 to 960 MHz (DL)
n12: 699 to 716 MHz (UL), 729 to 746 MHz (DL)
n20: 832 to 862 MHz (UL), 791 to 821 MHz (DL)
n28: 703 to 748 MHz (UL), 758 to 803 MHz (DL)

n41: 2496 to 2690 MHz (UL/DL)

n66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL) n71: 663 to 698 MHz (UL), 617 to 652 MHz (DL)

n77: 3300 to 4200 MHz (UL/DL) n78: 3300 to 3800 MHz (UL/DL) n79: 4400 to 5000 MHz (UL/DL)

Wireless protocol standards

5GNR Air Interface

3GPP Rel15 5G NR sub-6

LTE Rel14

20 layers and 2 Gbps downlink (DL) throughput -4×4 MIMO across 5x CA

200 Mbps uplink (UL) throughput - 40 MHz ULCA and 256 QAM

WCDMA

R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B)

GPS bands GPS: L1 (1575.42MHz); L5 (1176MHz)

GLONASS: L1 (1602MHz) BeidouB1(1561.098MHz)

Galileo E1 (1575.42); E5a (1176MHz)

Maximum data rates 5G sub 6G: 3.8 Gbps

LTE: ue-CategoryDL 20, (DL : 2 Gbps) ue-CategoryUL 13 , (UL: 150Mbps)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm in all band except B41

LTE B41 HPUE = 26dBm HSPA+: 23.5 dBm

Maximum power 5G Sub 6 : 2500 mA consumption LTF: 1 300 mA (peal

LTE: 1,300 mA (peak); 1100 mA (average)
HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Technical Specifications

Weight 8 g

Dimensions 42 mm × 30 mm × 2.6 mm

(Length x Width x

Thickness)

1. 5G module is an optional feature that must be configured at purchase. AT&T and T-Mobile networks supported in the U.S. Module designed for 5G networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP, requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 5G not available on all products, in all regions. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select countries, where carrier supported.



Technical Specifications

POWER

AC Adapter 65 Watt nPFC Dimensions Slim USB Type-C® Straight 1 m

88x53.5x21mm Weiaht unit: 220g +/- 10g Input 100 to 240 VAC

> **Input Efficiency** 81.5% min at 115 Vac/ 230Vac @ 5V/3A

86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

Input frequency range

47 ~ 63 Hz

Input AC current

1.6 A at 90 VAC and maximum load

Output **Output power** 65W

> **DC** output 5V/9V/12V/15V/20V Hold-up time 5ms at 115 Vac input

Output current limit <8.0A

Connector USB Type-C

Environmental Design Operating temperature 32°F to 95°F (0° to 35°C)

Non-operating (storage)

temperature

Altitude

0 to 16,400 ft (0 to 5000m)

-4°F to 185°F (-20° to 85°C)

Humidity 5% to 95% **Storage Humidity** 5% to 95%

EMI and Safety Certifications

Eq:

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 100,000 hours at 25°C ambient condition.

AC Adapter 65 Watt nPFC Dimensions Standard USB Type-C® Straight 1 m

90.0x51x28.5mm

Weight unit: 250g +/- 10g Input 100 to 240 VAC

> **Input Efficiency** 81.5% min at 115 Vac/ 230Vac @ 5V/3A

> > 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

Input frequency range 47 ~ 63 Hz

Input AC current 1.6 A at 90 VAC and maximum load

Output **Output power** 65 W

> **DC** output 5V/9V/12V/15V/20V Hold-up time 5ms at 115 Vac input

Output current limit 8.0A Max.

Technical Specifications

Connector USB TYPE C

Environmental Design Operating temperature 32°F to 95°F (0°to 35°C)

Non-operating (storage) -4°F to 185°F (-20°to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

Safety Certifications - CE Mark - full compliance with LVD and EMC directives

- Worldwide safety standards -IEC60950, EN60950, UL60950, UL62368, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022

Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. - MTBF - over 200,000 hours at 25°C ambient condition.

HP 4-cell Long Life Li-Ion(56Wh)

Dimensions (H x W x L) 5.25x85.00x274.00 mm

Weight 0.259 kg

Cells/Type 4cell Lithium-Ion Polymer cell / 446872

Energy Voltage 8.8V/7.7V

Amp-hour capacity 7.3Ah/7.0Ah

Watt-hour capacity 56 Wh

Temperature

Operating (Charging) 32° to 113° F (0° to 45° C)
Operating (Discharging) 14° to 122° F (-10° to 60° C)

Optional Travel Battery

Available

No

FINGERPRINT READER

Model: Model: Synaptics Validity VFS7552 touch sensor

Mobile Voltage Operation: Mobile Voltage Operation: 3.0V to 3.6V

Operating Temperature: Operating Temperature: 14° – 167°F (-10°-75°C)

Current Consumption Image: Current Consumption Image: 36mA peak **Low Latency Wait For Finger:** Low Latency Wait For Finger: 950 uA

Capture Rate: Capture Rate: 30 cm/sec

ESD Resistance: ESD Resistance: IEC 61000-4-2 4B (+15KV)

Detection Matrix: Detection Matrix: 200*1 (Plus another secondary line) / 508 dpi / 10mm sensor area

FRR (False Reject Rate) / FAR FRR (False Reject Rate) / FAR (False Acceptance Rate): FRR ~ 1% @ 1:50K FAR

(False Acceptance Rate):

Technical Specifications

ENVIRONMENTAL DATA

Eco-Label	This product has received or is in the process of being certified to the following approvals and may be			
Certifications & declarations	 IT ECO declaration US ENERGY STAR® US Federal Energy Management Program (FEMP) EPEAT⁰ Gold registered in the United States. See http://www.epeat.net for registration status in your country. TCO 8.0 China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Korea Eco-label Japan PC Green label* 			
uecturucions				
Sustainable Impact	Ocean-bound plastic in sp	eaker enclosure and bezel ¹		
Specifications	 Ocean-bound plastic in speaker enclosure and bezel¹ 10% post-consumer recycled plastic ² Low halogen³ Bulk packaging available 			
	 Percentage of ocean-bound plastic contained in each component varies by product Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard. External power supplies, WWAN modules, power cords, cables and peripherals excluded. outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers. 			
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".			
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation (Sort	5.07 W	5.26 W	4.92 W	
idle)				
Normal Operation (Long idle)	0.73 W	0.82 W	0.78 W	
Sleep	0.73 W	0.82 W	0.78 W	
Off	0.30 W	0.32 W	0.29 W	



Technical Specifications

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Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	16 BTU/hr	16 BTU/hr	16 BTU/hr
Normal Operation (Long idle)	3 BTU/hr	3 BTU/hr	2 BTU/hr
Sleep	3 BTU/hr	3 BTU/hr	2 BTU/hr
Off	1 BTU/hr	1 BTU/hr	1 BTU/hr

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise	Sound Power	Sound Pressure	
Emissions (in accordance with ISO 7779 and ISO 9296)	(L _{WAd} , bels)	(L _{pAm} , decibels)	
Typically Configured — Idle	2.7	13.8	
Fixed Disk – Random writes	3.0	19.8	
Optical Drive – Sequential reads	3.4	22.7	
Longevity and	This product can be upgraded possibly extending its useful life by several years. Upgradeable		

Longevity and Upgrading

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Technical Specifications

Additional Information					
	 directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. 				
	This product is in compliance with California Proposition 65 (State of California; Safe				
		ring Water and Toxic Enforcement Act of 1986).			
		product is in compliance with the IEEE 1680 (EPEAT) standa	ard at the Gold level, see		
		epeat.net ics parts weighing over 25 grams used in the product are n	narked per ISO11469 and		
		product is 11.07% recycle-able when properly disposed of	at end of life.		
Packaging Materials	External:	PAPER/Corrugated	215 g		
		PAPER/Corrugated	49 g		
	Internal:	PLASTIC/polypropylene	3 g		
		PLASTIC/Polyethylene low density	111 g		
		PAPER/Molded pulp	102 g		
		PAPER/Molded pulp	154 g		
		ackaging material contains at least 0% recycled content. ed paper packaging materials contains at least 64% recycl	-4		
RoHS Compliance	HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam. We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products. We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve. To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.				
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html): Asbestos Certain Azo Colorants Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Bis(2-Ethylhexyl) phthalate (DEHP) Benzyl butyl phthalate (BBP) Dibutyl phthalate (DBP) Diisobutyl phthalate (DIBP) 				

Technical Specifications

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Lead and Lead compounds Mercuric Oxide Batteries Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Ethers (PBBEs) Polychlorinated Biphenyl (PCB) Polychlorinated Biphenyl (PCB) Polychlorinated Biphenyl (PCB) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) Packaging Usage HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle Management and product packaging materials are marked according to ISO 11469 and DIN 6120 standards. HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle management and product					
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Technical Specifications

HP, Inc. Corporate	For more information about HP's commitment to the environment:
Environmental	
Information	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842
	and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

COUNTRY OF ORIGIN

China



Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part Number
Audio	HP Wired Thunderbolt Audio Module	3AQ21AA,3AQ21UT,3AQ21ET
	HP Wired USB-A UC SPK Phone Black WIdow	4VW02AA
Case	HP Business 13.3 Sleeve	2UW00AA,2UW00UT,2UW00ET
	HP Business 14.1 Sleeve	2UW01A6
	HP Business 14.1 Sleeve	2UW01AA,2UW01UT,2UW01ET
	HP Business 15.6 Case	2SC66A6
	HP Business 15.6 Top Load	2SC66AA,2SC66UT,2SC66ET
	HP Business 17.3 Backpack	2SC67A6
	HP Business 17.3 Backpack	2SC67AA,2SC67UT,2SC67ET
	HP Business Slim 14.1 Top Load	2SC65A6
	HP Business Slim 14.1 Top Load	2SC65AA,2SC65UT,2SC65ET
	HP Business Slim 17.3 Top Load	2UW02A6
	HP Business Slim 17.3 Top Load	2UW02AA,2UW02UT,2UW02ET
	HP Executive 14.1 Tote	6KD10AA,6KD10UT,6KD10ET
	HP Executive 15.6 Backpack	6KD07AA,6KD07UT,6KD07ET
	HP Executive 15.6 Top Load	6KD06AA,6KD06UT,6KD06ET
	HP Executive 17.3 Backpack	6KD05AA,6KD05UT,6KD05A9,6K D05ET
	HP Executive 17.3 Top Load	6KD08AA,6KD08UT,6KD08ET
	HP Executive Convertible 14.1 Tote	5KN27AA
	HP Executive Leather 15.6 Top Load	6KD09AA,6KD09UT,6KD09ET
	HP Executive Slim 14.1 Top Load	6KD04AA,6KD04UT,6KD04ET
	HP Prelude G2 15.6 Backpack	1E7D6A6
	HP Prelude G2 15.6 Backpack	2Z8P3AA,1E7D6AA
	HP Prelude G2 15.6 Top Load	1E7D7A6
	HP Prelude G2 15.6 Top Load	2Z8P4AA,1E7D7AA
	HP Prelude Pro Recycled 15.6 Backpack	1X644A6
	HP Prelude Pro Recycled 15.6 Backpack	1X644AA,1X644UT,1X644ET
	HP Prelude Pro Recycled 15.6 Top Load	1X645A6
	HP Prelude Pro Recycled 15.6 Top Load	1X645AA,1X645UT,1X645ET
	HP Renew Business 14.1 Laptop Bag AMO	3E5F9A6
	HP Renew Business 14.1 Laptop Bag	3E5F9AA,3E5F9UT,3E5F9ET
	HP Renew Business 14.1 Laptop Sleeve	3E2U7AA,3E2U7UT,3E2U7ET
	HP Renew Business 14.1 Sleeve	3E2U7A6
	HP Renew Business 15.6 Laptop Bag	3E5F8A6
	HP Renew Business 15.6 Laptop Bag	3E5F8AA,3E5F8UT,3E5F8ET
	HP Renew Business 17.3 Laptop Backpack	3E2U5A6
	HP Renew Business 17.3 Laptop Backpack	3E2U5AA,3E2U5UT,3E2U5ET



Options and Accessories (sold separately and availability may vary by country)

HP Renew Business 17.3 Laptop Bag 3E2U6AA,3E2U6UT

Digital Pen HP Rechargeable Active Pen G3 6SG43AA

Docks HP USB-C/A 120W G2 Universal Dock 5TW13AA, 5TW13ET, 5TW13UT

HP Thunderbolt 120W G2 Dock 6HP48AA, 2UK37AA, 2UK37ET

HP Thunderbolt 120W G2 Dock w/Audio 3YE87AA, 3YE87ET

HP Thunderbolt 230W G2 Dock 2UK38AA, 2UK38UT, 2UK38ET

HP Thunderbolt 230W G2 Dock w/Combo Cable 3TR87AA, 3TR87UT, 3TR87ET

HP USB-C 120W G5 Dock 26D32AA, 5TW10XX

HP USB-C Mini Dock 1PM64AA,1PM64UT, 1PM64ET

HP USB-C Travel Dock G2 7PJ38AA,7PJ38UT,7PJ38ET

Input/Output HP WL USB Agnes Keyboard T6U20AA, T6U20UT

HP Collaboration WL Wanda Bluetooth Keyboard Z9N39AA, Z9N39UT

HP Wired Desktop 320K Keyboard 9SR37AA, 9SR37UT, 9SR37ET
HP 125 WD USB Keyboard 266C9AA, 266C9UT, 266C9ET

HP Wireless Rechargeable 950MK Mouse and Keyboard 3M165AA, 3M165UT

HP USB Essential Keyboard/Mouse H6L29AA

HP Wired Desktop 320MK Mouse and Keyboard 9SR36AA, 9SR36UT, 9SR36ET

HP Slim Wireless Keyboard and Mouse T6L04AA, T6L04UT

HP Wired Desktop 320M Mouse 9VA80AA, 9VA80UT, 9VA80ET

HP Wired Mouse 265A9AA, 265A9UT, 265A9ET

HP LSR Wired Mouse 265D9AA, 265D9UT, 265D9UT

HP USB 320M Wired Mouse 9VA80AA,9VA80UT,9VA80ET

HP Comfort Grip USB Wireless Mouse H2L63AA, H2L63UT

HP Bluetooth Fingerprint Reader USB Mouse 4TS44AA,4TS44UT,4TS44ET

HP Bluetooth Travel Bluetooth Mouse 6SP30AA,6SP30UT,6SP30ET

HP Creator USB-A+Bluetooth 935 Wireless Mouse Black 1D0K8AA, 1D0K8ET, 1D0K8UT

HP Presenter Bluetooth 4.2 Bluetooth Mouse 2CE30AA,2CE30UT,2CE30ET

HP UltraMobile USB-A Wireless Mouse H6F25AA, H6F25UT

HP USB-A Fingerprint Reader USB Mouse 4TS44AA, 4TS44UT, 4TS44ET

HP USB-A Laser 3 Button USB Mouse H4B81AA, H4B81ET

HP USB Premium USB Mouse 1JR32AA,1JR32UT

HP USB Premium Wireless Mouse 1JR31AA,1JR31UT

HP USB Travel USB Mouse G1K28AA, G1K28ET

HP Multi-Device 635 Black Wireless Mouse 1D0K2AA

HP USB-A+Bluetooth Travel Bluetooth Mouse 6SP30AA, 6SP30UT, 6SP30ET

HP HDMI to DVI Adapter F5A28AA

HP HDMI to VGA Adapter H4F02AA, H4F02UT, H4F02ET

Power

Options and Accessories (sold separately and availability may vary by country)

HP USB 3.0 to Gigabit Adapter N7P47AA

HP USB-C to 4.5mm Adapter 4ST73AA

2PC54AA.1WC36UT.1WC36AA HP USB-C to HDMI 2.0 Adapter

HP USB-C to RJ45 Adapter V8Y76AA, V7W66AA, V7W66UT

HP USB-C to USB-A Adapter N2Z63AA, N2Z63UT

HP 4.5 mm and USB-C Dock Adapter G2 HP USB-C to USB-A Hub Jake

Z8W90AA, Z6A00XX

HP USB-C to USB-C Cable Blight 5AR72AA

HP USB-C to VGA Adapter P7Z54AA, N9K76AA, N9K76UT

HP 45W USB-C LC Dali AC Power Adapter 1MZ01AA

> HP 65W USB-C Auto Chevy AC Power Adapter 5TQ76AA,5TQ76UT,5TQ76ET

> HP 65W USB-C Hades AC Power Adapter X7W50AA,1HE08XX

> HP 65W USB-C LC AC Power Adapter 1P3K6AA

> HP 90W USB-C Gaia AC Power Adapter 2LN85AA

> **HP USB Power Bank** N9F71AA, N9F71UT

> **HP USB-C Essential Power Bank** 3TB55AA,3TB55UT

Storage **HP USB DVD-Writer EXT ODD** Y3T76AA, F2B56AA, F2B56UT,

F2B56ET

6UW42AA

6LX61AA

1HE07AA,1HE07UT

Security HP Nano Cable Lock 1AJ39AA,1AJ39UT

HP Sure Key Cable Lock

HP 45W USB-C G2 Zeus AC Power Adapter

HP Nano Master Keyed Cable Lock 1AJ40AA, 1AJ40UT



Summary of Changes

Date of change:	Version History:		Description of change:
January 29, 2021	V1 to V2	Update	USB Ports
February 10, 2021	V2 to V3	Added	Environmental Data
March 1, 2021	V3 to V4	Added	Low Blue Light feature, Update Processors and Storage Section
March 4, 2021	V4 to V5	Update	Battery Life and Low Blue Light Disclamer
March 9, 2021	V5 to V6	Added	Brightview to Display section
April 1, 2021	V6 to V7	Updated	Environmental Data
April 16, 2021	V7 to V8	Update	Options and Accessories
April 19, 2021	V8 to V9	Update	TechSpecs
May 6, 2021	V9 to V10	Add	HP Smart Support
May 21, 2021	V10 to V11	Update	Options and Accessories section
May 27, 2021	V11 to V12	Update	HP Pro Security Edition to HP Wolf Pro Security Edition
June 11, 2021	V12 to V13	Remove	HP WorkWell from Software and Security section

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